

## SilGrip\* PSA6574 Pressure Sensitive Adhesive

### SilGrip\* PSA6574 Pressure Sensitive Adhesive

#### Description

PSA6574 silicone pressure sensitive adhesive is a toluene solution of phenyl based polysiloxane gum and resin. It is supplied at 55 percent silicone solids and may be further diluted with aromatic, aliphatic or chlorinated solvents. PSA6574 may be blended with SR545 resin dispersion to obtain specific performance properties. PSA6574 adhesive has been found useful in coating of film and fabric substrates for manufacturing industrial pressure sensitive tapes, label stock for extremely high and low temperature applications and transfer tapes. It may be an excellent choice for tapes used in plasma/flame spray applications due to its superior thermal stability.

#### Key Features and Benefits

- Wide temperature range performance, maintains good shear and tack properties at intermittent temperatures up to 500°F
- Adhesion to a wide variety of surfaces including low energy surfaces (silicones, fluoropolymers, polyolefines)
- Resistance to moisture, weathering (ozone, sunlight), chemical (acids, alkalis, oils) and biological (fungus) attack
- Minimum silicone residue on applied surfaces

#### Typical Physical Properties

Property	Value
Silicone Solids, %	55

Specific Gravity	0.98
Density, lbs/gal	8.3
Viscosity @ 25° (77°F ), cps (Brookfield RVF, #5 spindle, 4 rpm)	17,000
Color	Light Straw
Flash Point, PMCC, ° C (° F)	11 (52)
Solvent	Toluene, VM& P Naphtha

**TYPICAL CURED ADHESIVE PROPERTIES**

• Peel Adhesion <sup>(1)</sup> , g/inch	2700
• Tack <sup>(2)</sup> , g/cm <sup>2</sup>	1420

(1) 2 mil dry adhesive thickness, 1mil polyester film, uncatalyzed, curing cycle: 10 min air dry, 90 sec at 177°C

(2) Polyken Tack Tester, 1000g weight, 1sec dwell time, 1 cm/sec draw speed, 2 mil dry adhesive thickness, 1mil polyester film, uncatalyzed, curing cycle: 10 min air dry, 90 sec at 177°C

The properties of a cured silicone adhesive are affected by several factors such as type and amount of catalyst, cure cycle, adhesive thickness and backing type and thickness. Higher benzoyl peroxide catalyst concentration will increase cohesive strength of the adhesive and improve shear strength, but it will reduce its adhesive strength resulting in lower tack and peel values.

**Patent Status**

Standard copy to come

**Product Safety, Handling and Storage**

The warranty period is 6 months from date of shipment from Momentive Performance Materials if stored in the original unopened container at 25°C (77°F).

Standard copy to come

## **Processing Recommendations**

### **Application**

PSA6574 silicone adhesive is supplied at a viscosity suitable for conventional tape coating equipment. If necessary, it may be thinned with toluene, xylene or other compatible solvents. After the adhesive is applied to the backing, it is exposed to a two step process: solvent removal and curing.

### **Solvent Removal**

To achieve optimum adhesive properties, it is essential to optimize the drying step of the process in order to assure that the solvent is removed from the adhesive film before the curing step of the process starts. Improper drying will result in residual solvent entrapment within the adhesive. If the adhesive is then exposed to temperatures higher than 93.5 ° C (200 ° F), decomposing peroxide catalyst can cause crosslinking reaction between solvent and adhesive through methyl groups on siloxane chains and on solvent molecules and adversely affect the properties of the adhesive. Typical temperature range for the drying step of the process is 83 ° C (180 ° F) to 90 ° C (194 ° F). A typical drying cycle is 2 minutes at 90 ° C (194 ° F).

### **Curing Process**

Once the solvent is removed from the adhesive film, the peroxide cure should be initiated by exposure to heat. A typical curing cycle is 2 minutes at 165 ° C (329 ° F). Longer exposure time and higher temperature, up to 204 ° C (400 ° F), can be used without adverse effects. The exact conditions required to achieve a complete cure will depend on oven length and efficiency, peroxide type and type of substrate used, and should be established during experimental trials on the machine.

### **Catalysts**

High purity, 98% benzoyl peroxide <sup>(3)</sup> in the quantity of 1 to 3% based on silicone solids, has been found to give the most consistent results in curing of silicone pressure sensitive adhesives. In applications requiring low temperature cure, 2,4-dichlorobenzoyl peroxide, which is activated at 132 ° C (270 ° F), can be used. It should be noted that 2,4-dichlorobenzoyl peroxide may generate polychlorinated biphenyls during the curing process. Please refer to Code of Federal Regulations, title 40, part 761 regarding incidental PCB byproducts if 2,4- dichlorobenzoyl peroxide is utilized.

The peroxide should be dispersed in solvent before it is mixed with the adhesive. Thorough mixing of the peroxide and adhesive to achieve homogeneous dispersion is essential for consistency of finished product.

(3) Available from: Elf Atochem North America, Inc.,

## Priming

In certain applications, the anchorage of the adhesive to the backing may be insufficient and the coating of a primer prior to the adhesive coating may be required.

A typical formulation for a primer may be found in Table1 below. The formulation may need to be adjusted depending on required bath life, coating equipment and backing material. The primer may be coated by direct gravure, wire wound rod or other coating technique suitable for solvent based coatings, and must be cured prior to adhesive application. The curing conditions will depend on equipment capabilities, substrate type and formulation used and should be established during experimental trials on the machine.

## Table1. Typical Primer <sup>(4)</sup> Formulation

Component	Parts by Weight
SS4195A-D1	13.3
SS4191B	0.3
SS4192c	0.5
SS4259c	0.5
Solvent <sup>(5)</sup>	85.4

(4) Refer to document #CDS5511, SS4195-D1 Primer for Phenyl Based Silicone Pressure Sensitive Adhesives, for more information

(5) Typical solvents: toluene, heptane, toluene/heptane mixtures

### Limitations

Standard copy to come

### お問合せ窓口

製品の価格、取り扱い状況およびご注文については、[Momentive.com/Contact us/ CustomerService/](http://Momentive.com/Contact us/CustomerService/)からカスタマーサービスへご連絡ください。

パンフレットおよび技術情報については、弊社ウェブサイト[www.momentive.com](http://www.momentive.com)をご覧ください。

### 免責条項:

モメンティブ・パフォーマンス・マテリアルズならびにその子会社および関係会社(以下、総称して「サプライヤー」といいます)の素材、製品およびサービスは、サプライヤーの標準販売条件に基づき販売されています。この標準販売条件は、該当する販売代理店契約または販売契約に含まれており、注文確認書や請求書の裏面に印刷され、また要求に応じて提供可能です。本書に記載の情報、推奨、または提言は、誠意をもって提供されていますが、サプライヤーは明示的にも黙示的にも、(i)本書に記載の結果が最終使用条件下でも得られること、および(ii)製品、素材、サービス、推奨または提言に取り入れられている設計の有効性もしくは安全性について、いかなる保証もいたしません。サプライヤーの標準販売条件に定めのあるものを除き、サプライヤーおよびその代理人は、本書に記載の素材、製品またはサービスの使用によって生じたいかなる損害に対しても責任を負わないものとします。サプライヤーの素材、サービス、推奨、または提言が、ユーザー自身の特定の使用目的に適しているか否かの判断については、各ユーザー自身が全面的に責任を負います。各ユーザーは、すべてのテストや分析を特定および実施して、サプライヤーの製品、素材、またはサービスが組み込ま

れている最終製品が安全であり、最終使用条件における使用に適していることを確認する必要があります。サプライヤーの署名入りの書面による合意がない限り、本書もしくはその他の文書または口頭による推奨または提言は、サプライヤーの標準販売条件の規定または本免責条項の変更、修正、優先、または権利放棄とはみなされないものとします。本書に含まれる素材、製品、サービスまたは設計の使用可能性または使用提案に関するいかなる記載も、当該使用または設計を対象とするサプライヤーの特許その他の知的財産権に基づくライセンスを付与することを意図してはならず、あるいはライセンスの付与と解釈してはならず、また、何らかの特許その他の知的財産権を侵害する素材、製品、サービスまたは設計の使用の提案を意図してはならず、また使用提案として解釈してはなりません。

Momentive および Momentiveのロゴは、Momentive Performance Materials Inc.の商標です。